

	TECH	INICAL DATA SH	EET	2/8	
RIGHT A	NGLE H2 RECE	ТҮРЕ	R107.003.010		
	REEL 1		Series : UMP		
PACKAGING Standard Unit Other 100 'W' option Contact us			SPECIFICATION		
ELECTRICAL CHARACTERISTICS			<u>ENVIRONMENTAL</u>		
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	1.05 + 0.030 NA - (NA	GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi	Operating temper Hermetic seal Panel leakage	rature -40/+125 ° C NA Atm.cm3/s NA	
Voltage rating100Veff MaxiDielectric withstanding voltage350Veff miniInsulation resistance1000MΩ mini		Veff mini	OTHERS CHARACTERISTICS		
			Assembly instruc Others :	ction	
MECHAN	ICAL CHARACTE	RISTICS	-		
Center contact retent Axial force – Matin Axial force – Oppor Torque	g end NA site end NA	N mini N mini N.cm mini			
Recommended torqu Mating Panel nut	NA	N.cm N.cm			
Mating life Weight	100 0.035	Cycles mini g			
Issue : 0415 A In the effort to improve necessary.	e our products, we reserve	the right to make cha	anges judged to be	RADIALL [®]	

TECHNICAL DATA SHEET

RIGHT ANGLE H2 RECEPTACLE SMT TYPE

REEL 100

R107.003.010

Series : UMP

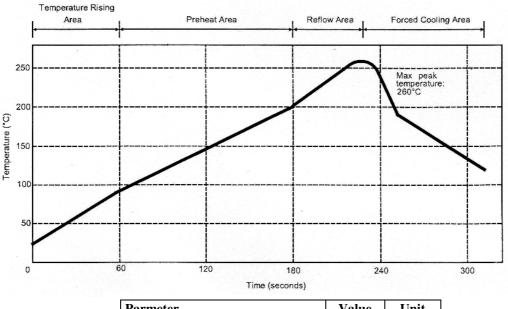
SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

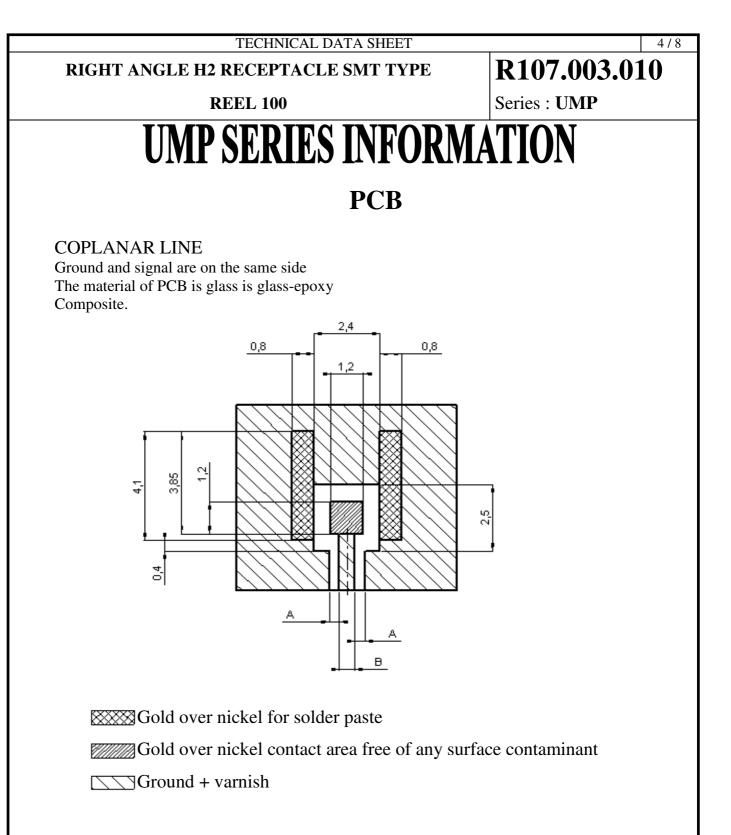
NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



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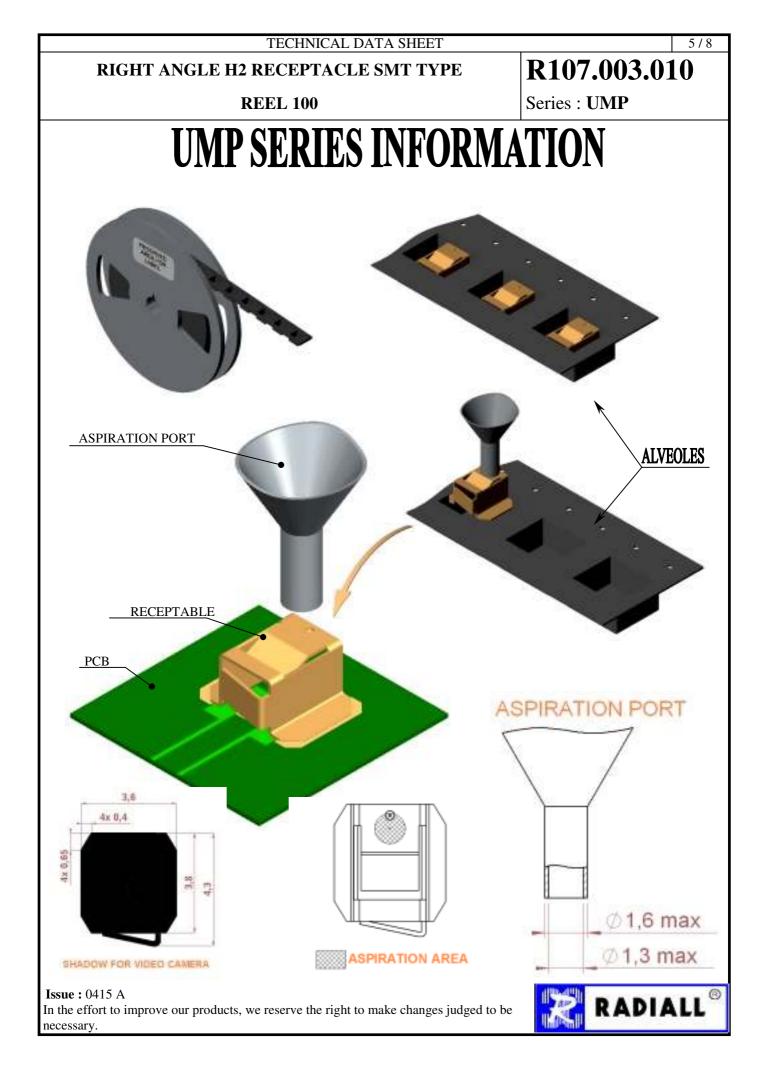


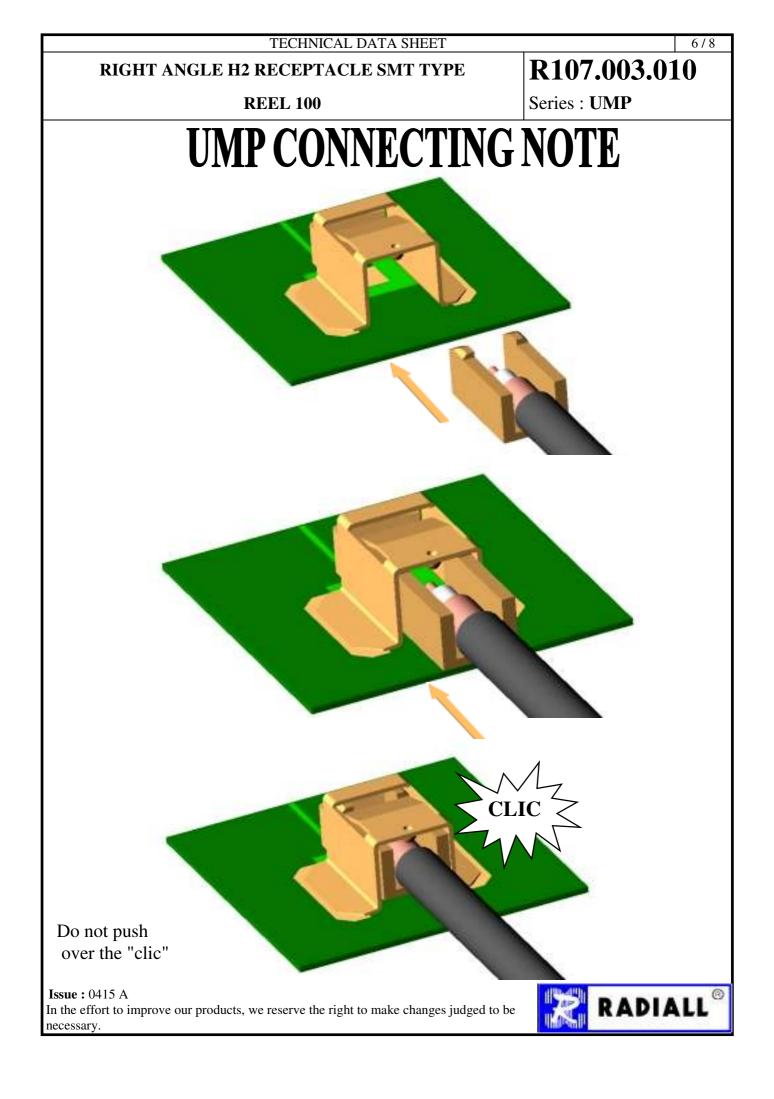
APPI	LICATION 75 Ω
WITH	l B = 0,55mm
PCF	3 thickness (mm)

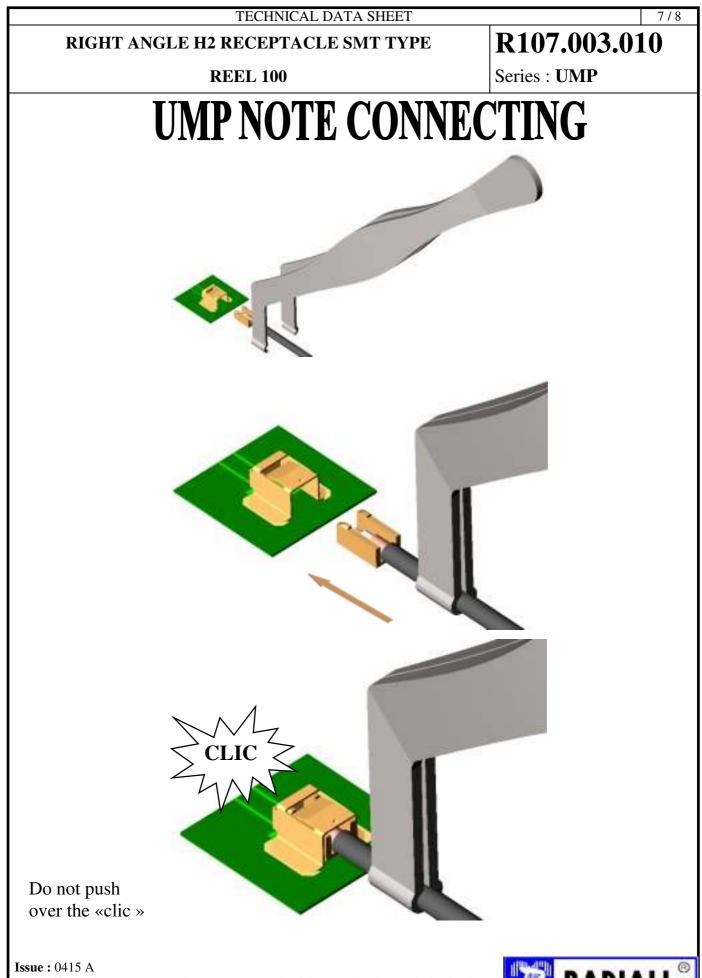
APPLICATION 50Ω

WITH B = 0,55mm		WITH B = 1,2mm		
PCB thickness (mm)	Coplanar ligne A (mm)	PCB thickness (mm)	Coplanar ligne A (mm)	
0,8	0,57	0,8	0,183	
1,0	0,45	1,0	0,190	
1,2	0,41	1,2	0,195	
1,6	0,37	1,6	0,20	



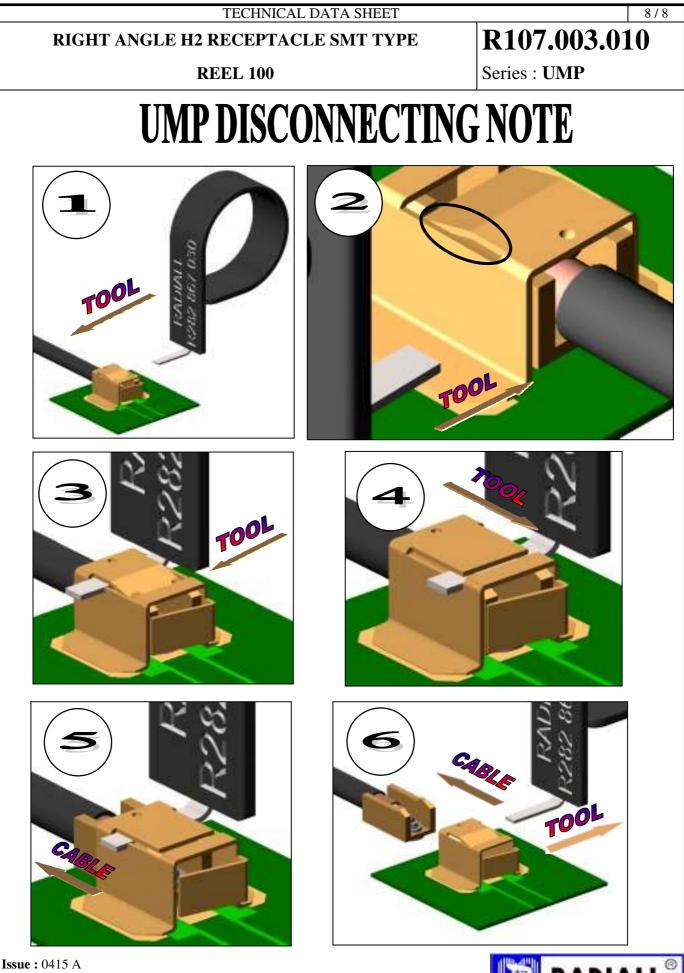






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